

**Amendments to the Claims:**

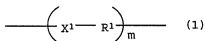
This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently Amended and Withdrawn) A resin composition used as an adhesive bonding a semiconductor chip or a heat dissipating member comprising a filler (A), the following compound (B) and a thermal radical initiator (C), and substantially not containing a photo polymerization initiator:

Compound (B):

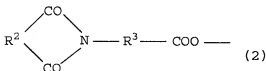
a compound containing a structure represented by the following formula (1) in a main chain and having at least one functional group represented by the following formula (2):

Formula (1):



wherein X<sup>1</sup> is -O-, -COO- or -OCOO-; R<sup>1</sup> is a hydrocarbon group having 1 to 6 carbons; "m" is an integer of ~~1 or more and 50 or less~~ from 1 to 50; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other;

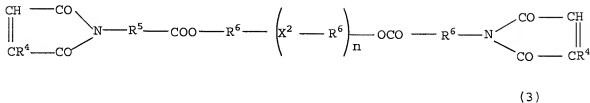
Formula (2):



wherein  $R^2$  is  $-C_2H_2-$  or  $-C_3H_4-$   ~~$-CH=CH-$~~  or  $-CH=CH-CH_2-$ ;  $R^3$  is a hydrocarbon group having 1 to 11 carbons; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

2. (Withdrawn) A resin composition according to Claim 1, wherein the filler (A) is silver powder.
3. (Withdrawn) A resin composition according to Claim 1, wherein  $X^1$  of the compound (B) is  $-O-$ .
4. (Withdrawn) A resin composition according to Claim 1, wherein  $R^1$  of the compound (B) is a hydrocarbon group having 3 to 6 carbons.
5. (Withdrawn) A resin composition according to Claim 4, wherein  $R^1$  of the compound (B) is at least one selected from the group consisting of  $-C_3H_6-$  and  $-C_4H_8-$ .
6. (Withdrawn) A resin composition according to Claim 1, wherein  $R^2$  is  $-C_2H_2-$  and  $R^3$  is  $-CH_2-$  in the compound (B).
7. (Withdrawn) A resin composition according to Claim 1, wherein the compound (B) has two functional groups represented by the formula (2).
8. (Currently Amended and Withdrawn) A resin composition according to Claim 1, wherein the compound (B) is a bis-maleimide compound (B') represented by the following formula (3):

Formula (3):



wherein  $\text{X}^2$  is  $-\text{O}-$ ,  $-\text{COO}-$  or  $-\text{OCOO}-$ ; each  $\text{R}^4$  is hydrogen atom or a methyl group; each  $\text{R}^5$  is a hydrocarbon group having 1 to 11 carbons; each  $\text{R}^6$  is a hydrocarbon group having 3 to 6 carbons; "n" is an integer of ~~1 or more and 50 or less~~ from 1 to 50; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

9. (Withdrawn) A resin composition according to Claim 8, wherein  $\text{X}^2$  of the bis-maleimide compound (B') represented by the formula (3) is  $-\text{O}-$ .

10. (Withdrawn) A resin composition according to Claim 8, wherein  $\text{R}^5$  of the bis-maleimide compound (B') represented by the formula (3) is a hydrocarbon group not containing an aromatic group.

11. (Withdrawn) A resin composition according to Claim 8, wherein  $\text{R}^5$  of the bis-maleimide compound (B') represented by the formula (3) has 1 to 5 carbons.

12. (Withdrawn) A resin composition according to Claim 8, wherein  $\text{R}^5$  of the bis-maleimide compound (B') represented by the formula (3) is  $-\text{CH}_2-$  or  $-\text{C}_5\text{H}_{10}-$ .

13. (Withdrawn) A resin composition according to Claim 8, wherein  $\text{R}^6$  of the

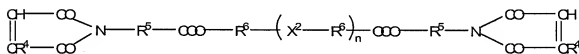
bis-maleimide compound (B') represented by the formula (3) is at least one selected from the group consisting of  $-C_3H_6-$  and  $-C_4H_8-$ .

14. (Currently Amended) A resin composition according to any of Claim 1, further comprising the following compound (D): used as an adhesive for bonding a semiconductor chip or a heat dissipating member, comprising at least a filler (A), the following compound (B), a thermal radical initiator (C) and the following compound (D), and substantially not containing a photo polymerization initiator;

Compound (B):

a bis-maleimide compound (B') represented by the following formula (3):

Formula (3)



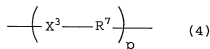
( 3 )

wherein  $X^2$  is  $-O-$ ,  $-COO-$  or  $-OCOO-$ ; each  $R^4$  is a hydrogen atom or a methyl group; each  $R^5$  is a hydrocarbon group having 1 to 11 carbons and containing no aromatic group; each  $R^6$  is a hydrocarbon group having 3 to 6 carbons and containing no aromatic group; "n" is an integer from 1 to 50; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other;

Compound (D):

a compound containing a structure represented by the formula (4) in a main chain and having at least one functional group having a polymerizable C-C unsaturated bond:

Formula (4):

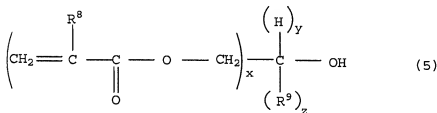


wherein  $\text{X}^3$  is  $-\text{O}-$ ,  $-\text{COO}-$  or  $-\text{OCOO}-$ ;  $\text{R}^7$  is a hydrocarbon group having 3 to 6 carbons; "p" is an integer of ~~1 or more and 50 or less~~ from 1 to 50; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

15. (Currently Amended) A resin composition according to ~~any of~~ Claim 1, further containing the following acrylic ester compound (E):

Acrylic ester compound (E):

Formula (5):



wherein  $\text{R}^8$  is hydrogen atom or a methyl group;  $\text{R}^9$  is a hydrocarbon group having 1 to 3 carbons; "x", "y" and "z" are in the relationship expressed by  $(x+y+z)=3$ ,  $1 \leq x \leq 3$ ,  $0 \leq y \leq 2$  and  $0 \leq z \leq 2$ ; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

16. (Previously Presented) A resin composition according to Claim 1, wherein  $\text{R}^8$  of the acrylic ester compound (E) represented by the formula (5) is a methyl group.

17. (Previously Presented) A resin composition according to Claim 1, wherein  $R^9$  of the acrylic ester compound (E) represented by the formula (5) is a methyl group.

18. (Previously Presented) A resin composition according to Claim 1, wherein  $R^8$  is a methyl group,  $R^9$  is a methyl group, and  $x=1$ ,  $y=1$ , and  $z=1$  in the acrylic ester compound (E) represented by the formula (5).

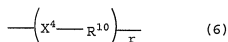
19. (Previously Presented) A resin composition according to Claim 1, wherein  $R^8$  is a methyl group,  $x=2$ ,  $y=1$  and  $z=0$  in the acrylic ester compound (E) represented by the formula (5).

20. (Currently Amended) A resin composition according to ~~any~~ of Claim 1, further comprising the following acrylamide compound (F):

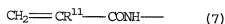
Acrylamide compound (F):

a compound containing a structure represented by the following formula (6) in a main chain and having at least one functional group represented by the following formula (7):

Formula (6):



Formula (7):



wherein  $X^4$  is  $-O-$ ,  $-COO-$  or  $-OCOO-$ ;  $R^{10}$  is a hydrocarbon group having 3 to 6 carbons;  $R^{11}$  is hydrogen atom or a methyl group; "r" is an integer of 1 or more and 50 or less from 1 to 50; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

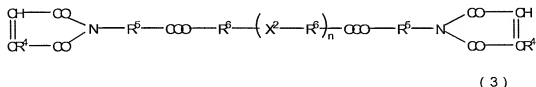
21. (Previously Presented) A resin composition according to Claim 20, wherein  $R^{10}$  of the structure represented by the formula (5) of the acrylamide compound E) is at least one selected from the group consisting of  $-C_3H_6-$  and  $-C_4H_8-$ .

22. (Previously Presented) A resin composition according to Claim 20, wherein  $X^4$  of the structure represented by the formula (5) of the acrylamide compound (E) is  $-O-$ .

23. (Currently Amended) A resin composition ~~according to any of Claim 1, further containing the following allyl ester compound (G):~~ used as an adhesive for bonding a semiconductor chip or a heat dissipating member, comprising at least a filler (A), the following allyl ester compound (G), and substantially not containing a photo polymerization initiator:  
Compound (B):

a bis-maleimide compound (B') represented by the following formula (3):

Formula (3)



wherein  $X^2$  is  $-O-$ ,  $-COO-$  or  $-OCOO-$ ; each  $R^4$  is a hydrogen atom or a methyl group; each  $R^5$  is a hydrocarbon group having 1 to 11 carbons and containing no aromatic group; each  $R^6$  is a

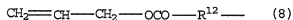
hydrocarbon group having 3 to 6 carbons and containing no aromatic group; "n" is an integer from 1 to 50; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

Allyl ester compound (G):

a compound having at least one functional group represented by the following formula

(8):

Formula (8):

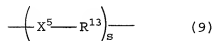


wherein  $\text{R}^{12}$  is a hydrocarbon group having 2 to 8 carbons.

24. (Original) A resin composition according to Claim 23, wherein  $\text{R}^{12}$  of the structure represented by the formula (8) of the allyl ester compound (G) does not contain an aromatic group.

25. (Currently Amended) A resin composition according to Claim 23, wherein the allyl ester compound (G) contains a structure represented by the following formula (9):

Formula (9):



wherein  $\text{X}^5$  is -O-, -COO- or -OCOO-;  $\text{R}^{13}$  is a hydrocarbon group having 3 to 6 carbons; "s" is an integer of ~~1 or more and 50 or less~~ from 1 to 50; and if the formula contains two or more parts



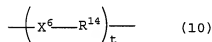
which are denoted by the same symbol, each of them may be the same or different from each other.

26. (Currently Amended) A resin composition according to ~~any of~~ Claim 1, further containing the following compound (H):

Compound (H):

a compound derived from a hydrocarbon having at least one C-C unsaturated bond in one molecule, which has a number average molecular weight of 500 to 5,000, contains a structure represented by the following formula (10) at its modified position, and has at least one functional group having a polymerizable C-C unsaturated bond:

Formula (10):



wherein X<sup>6</sup> is -O-, -COO- or -OCOO-; R<sup>14</sup> is a hydrocarbon group having 3 to 6 carbons; "t" is an integer of ~~1 or more and 50 or less~~ from 1 to 50; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

27. (Original) A resin composition according to Claim 26, wherein X<sup>6</sup> is -O- and R<sup>14</sup> is C<sub>4</sub>H<sub>8</sub> in the structure represented by the formula (10) of the compound (H).

28. (Previously Presented) A resin composition according to Claim 26, wherein a hydrocarbon led to the compound (H) and having at least one C-C unsaturated bond in one molecule is a butadiene polymer.

29. (Previously Presented) A resin composition according to Claim 26, wherein a hydrocarbon led to the compound (H) and having at least one C-C unsaturated bond in one molecule is an isoprene polymer.
30. (Previously Presented) A resin composition according to Claim 26, wherein the polymerizable C-C unsaturated bond of the compound (H) is a (meth)acryloyl group.
31. (Currently Amended) A resin composition according to ~~any~~ Claim 1, further containing a reactive diluent (I).
32. (Original) A resin composition according to Claim 31, wherein the reactive diluent (I) is a vinyl compound which is in liquid form at room temperature other than the compounds (D) to (H).
33. (Withdrawn) A resin composition according to Claim 32, wherein the vinyl compound is a compound containing at least one (meth)acryloyl group.
34. (Withdrawn) A resin composition according to Claim 1, further containing a silane-based coupling agent (J).
35. (Withdrawn) A resin composition according to Claim 34, wherein the coupling agent (J) is a silane coupling agent having an S-S bond.
36. (Withdrawn) A resin composition according to Claim 34, wherein the coupling agent (J) further contains a silane coupling agent having a glycidyl group.

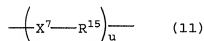
37. (Withdrawn) A resin composition according to Claim 1, containing a compound (K) having a glycidyl group other than the silane coupling agent having a glycidyl group.

38. (Currently Amended and Withdrawn) A resin composition according to Claim 1, further containing the following compound (L) and the following compound (M):

Compound (L):

a compound containing the following structure represented by the formula (11) in a main chain and having at least one glycidyl group:

Formula (11):



wherein  $\text{X}^7$  is  $-\text{O}-$ ,  $-\text{COO}-$  or  $-\text{OCOO}-$ ;  $\text{R}^{15}$  is a hydrocarbon group having 3 to 6 carbons; "u" is an integer of ~~2 or more and 50 or less~~ from 2 to 50; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other;

Compound (M):

a compound having a functional group which can react with the glycidyl group of the compound (L).

39. (Withdrawn) A compound according to Claim 38, wherein the repeating unit ( $\text{X}^7\text{-R}^{15}$ ) of the compound (L) is the same as the repeating unit ( $\text{X}^1\text{-R}^1$ ) of the compound (M).

40. (Withdrawn) A semiconductor device containing the resin composition according to Claim 1 as a die attach material.

41. (Withdrawn) A semiconductor device containing the resin composition according to Claim 1 as a material for bonding a heat dissipating member.